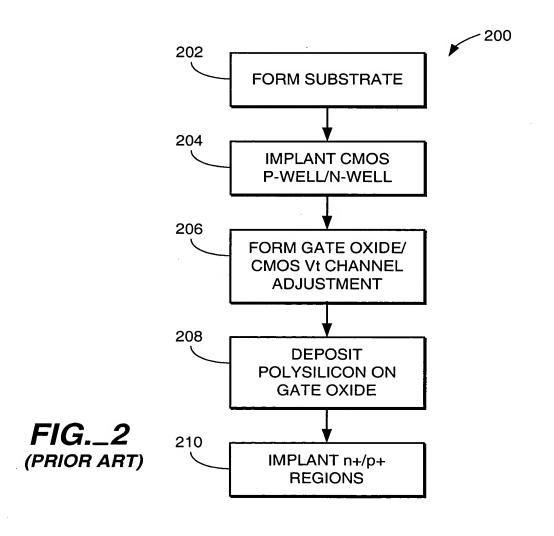
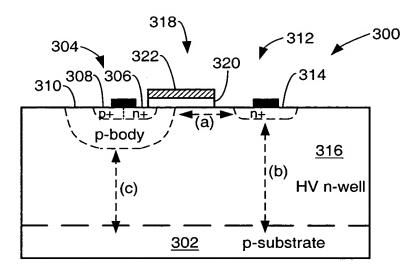


FIG._1 (PRIOR ART)

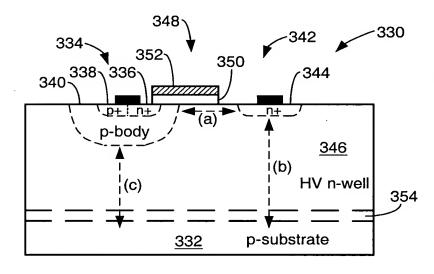


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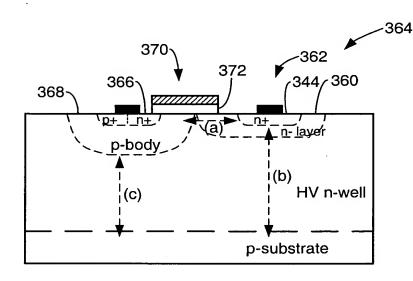
P-Body implanted after gate formation disrupts CMOS thermal budget

> FIG._3A (PRIOR ART)



P-Body implanted after gate formation disrupts CMOS thermal budget

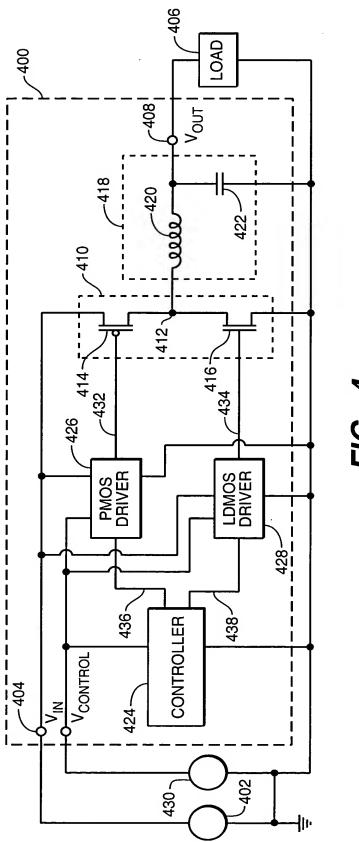
> FIG._3B (PRIOR ART)



P-Body implanted after gate formation disrupts CMOS thermal budget

> FIG._3C (PRIOR ART)

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F/G._4

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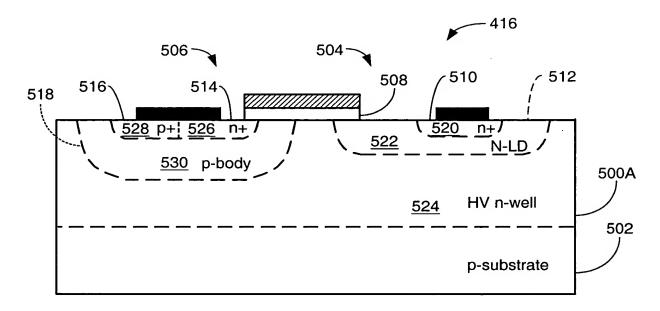


FIG._5A

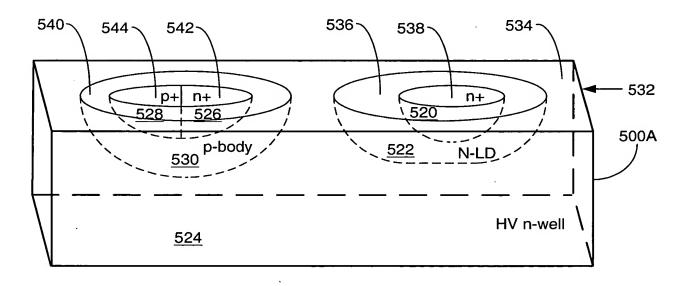
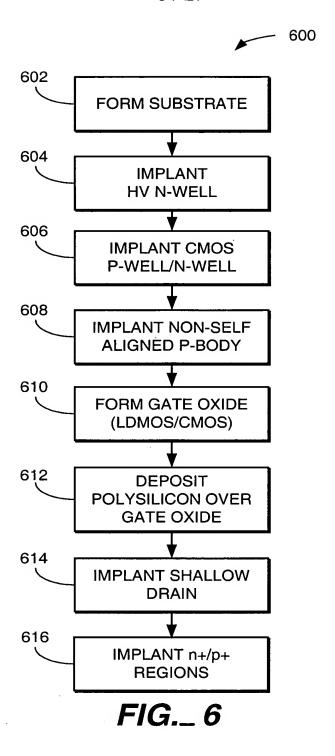
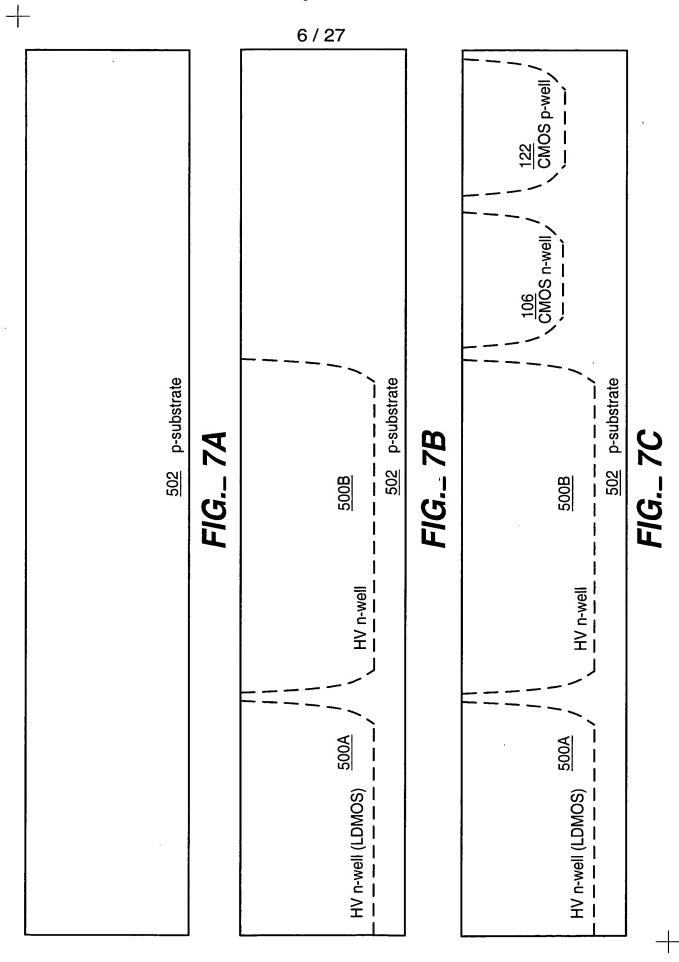


FIG._5B

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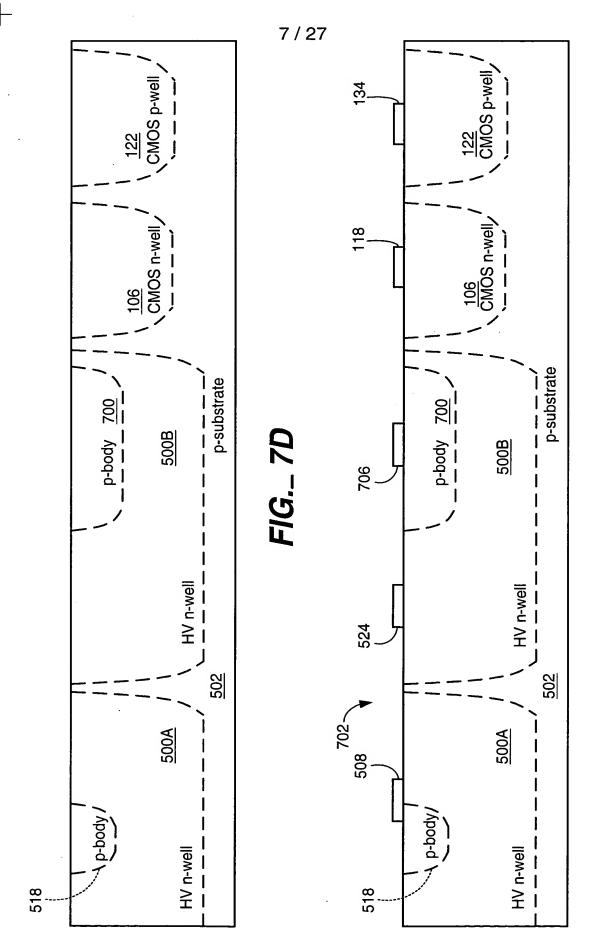
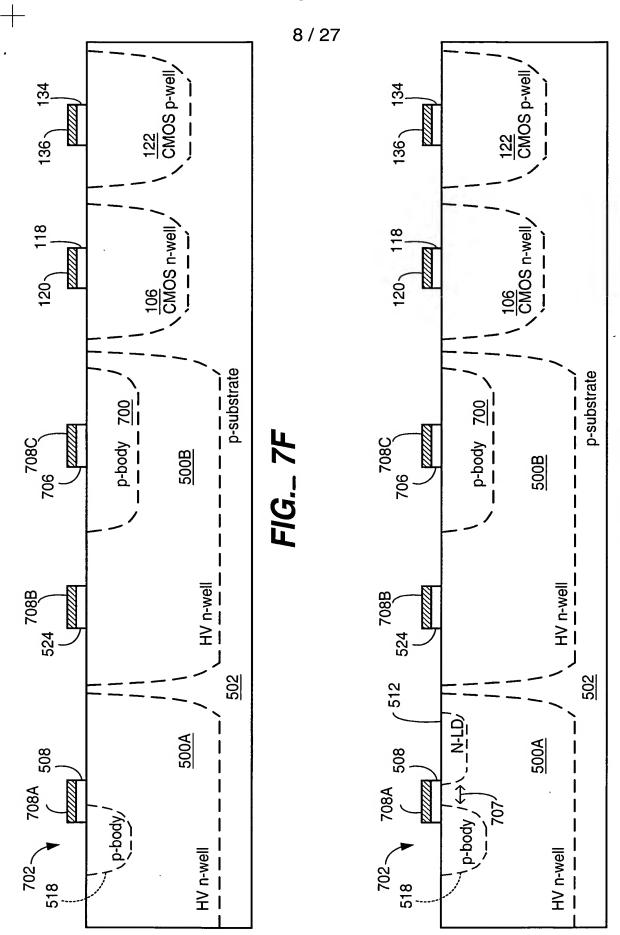


FIG._ 7E



F/G._ 7G

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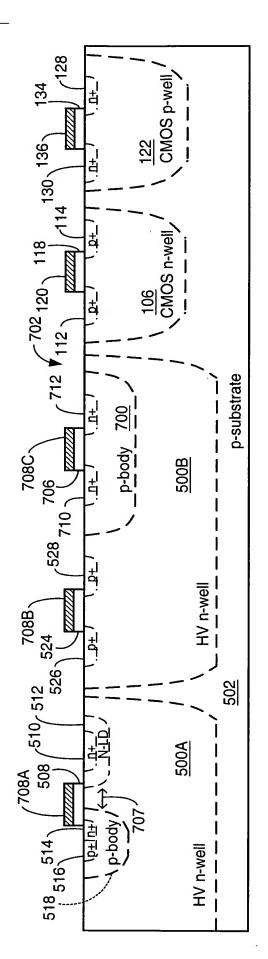


FIG._7H

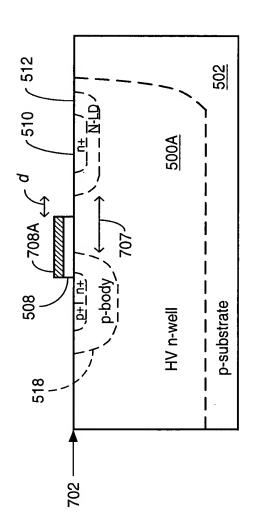
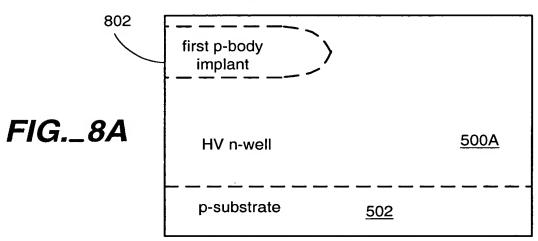
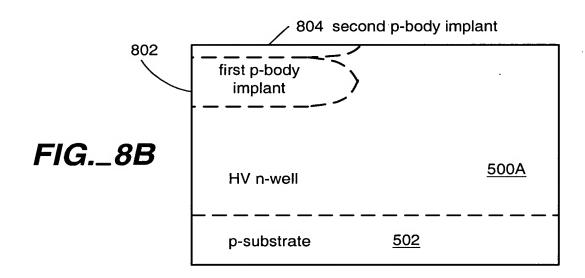
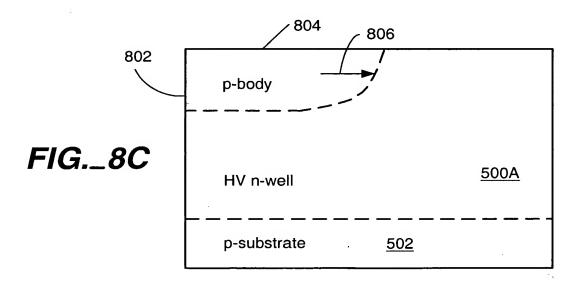


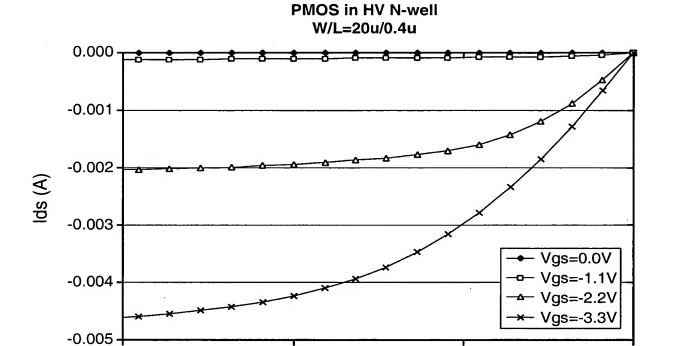
FIG._ 9











-2.2

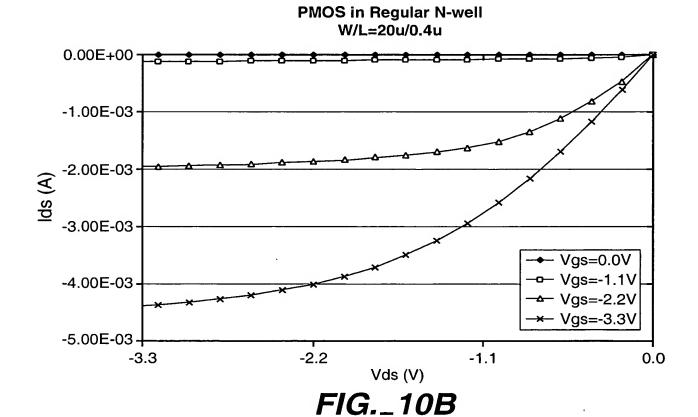
-3.3

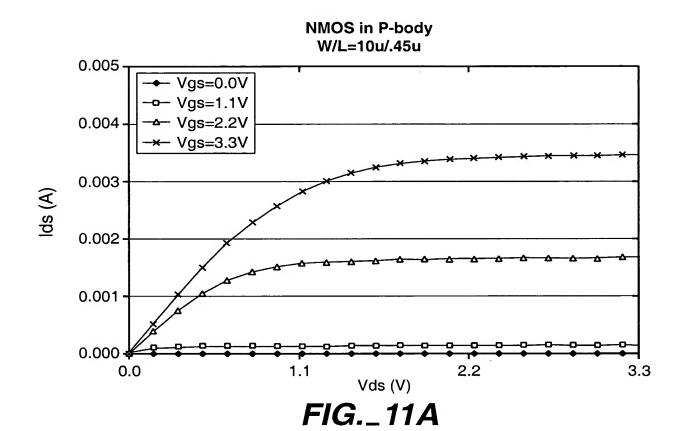
FIG._10A

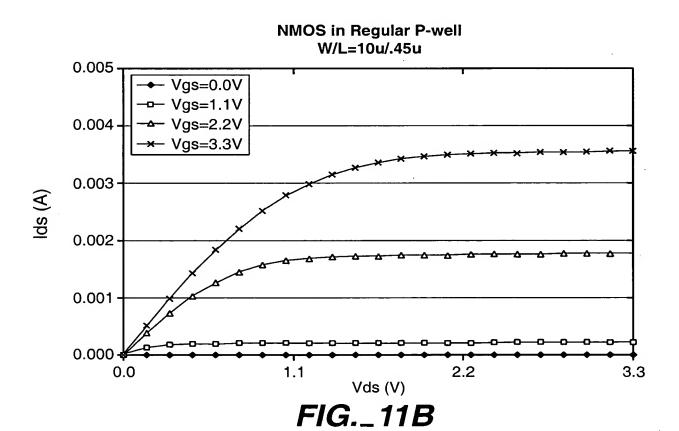
Vds (V)

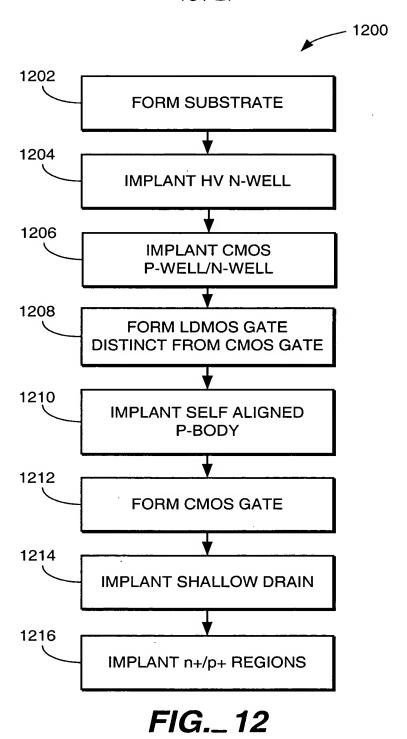
-1.1

0.0

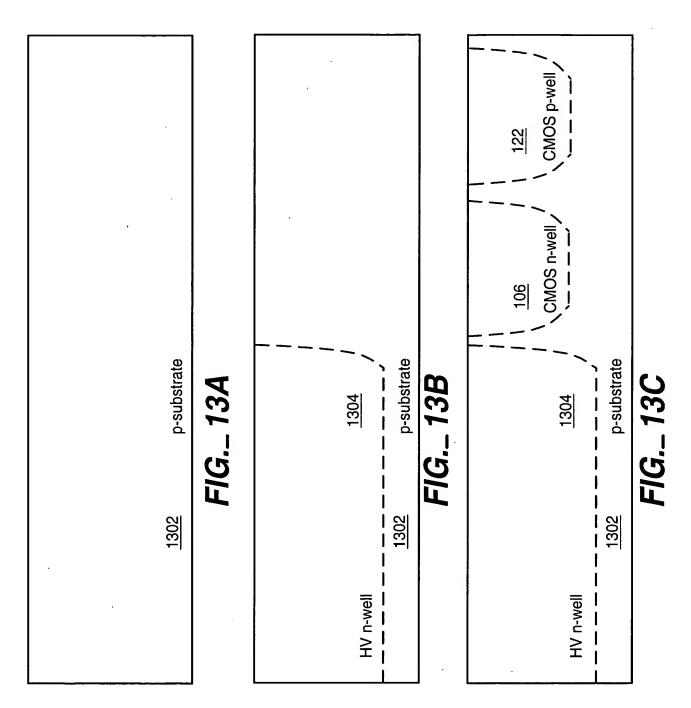




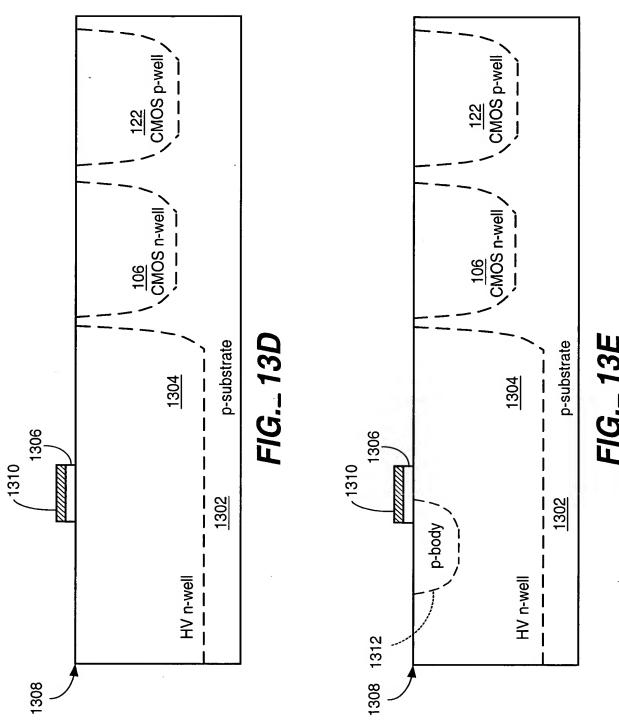




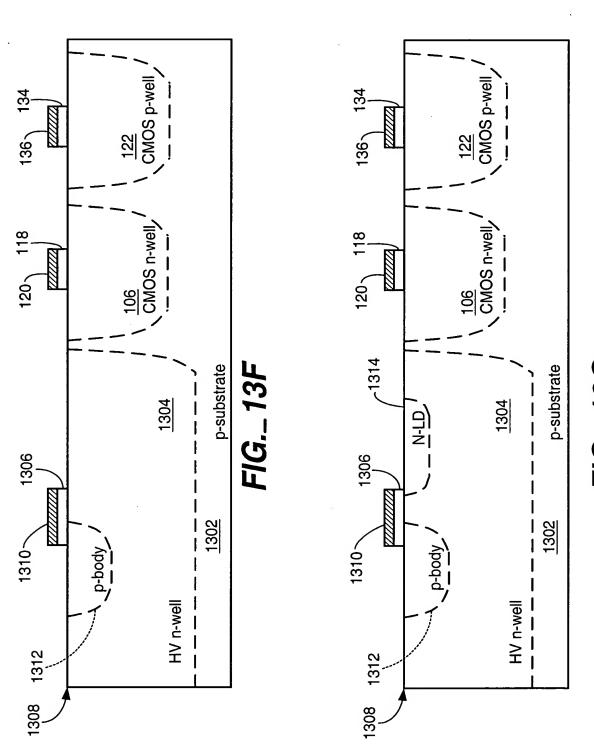
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F/G._ 13G

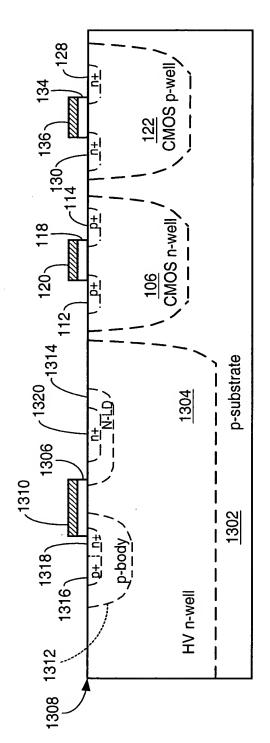


FIG._ 13H

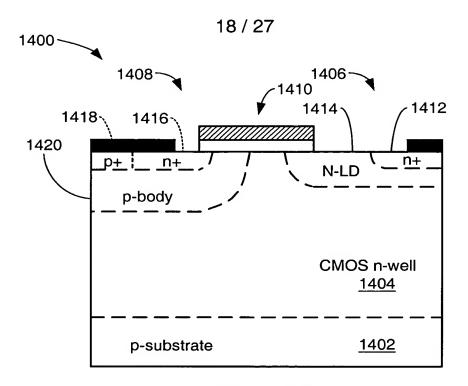


FIG._ 14

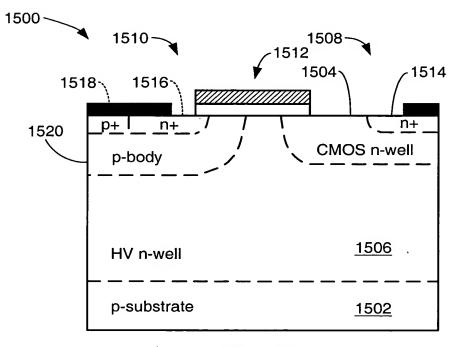


FIG._15

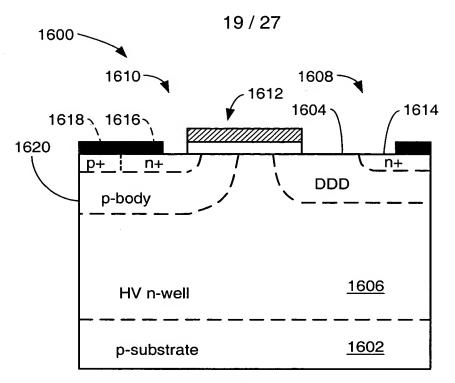


FIG._ 16

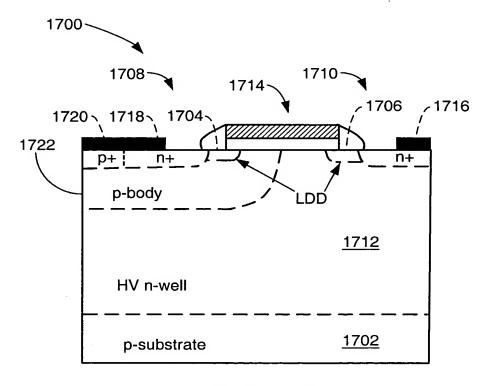


FIG._17

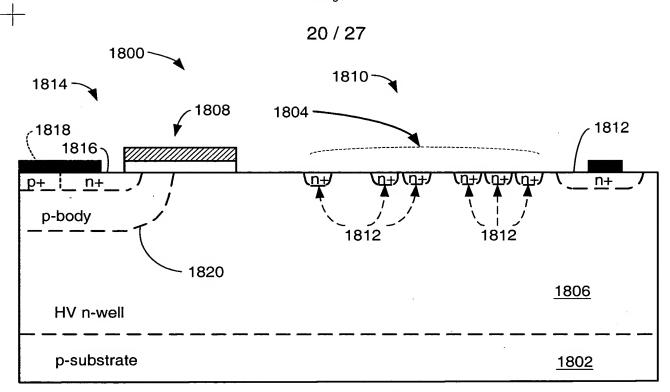


FIG._ 18

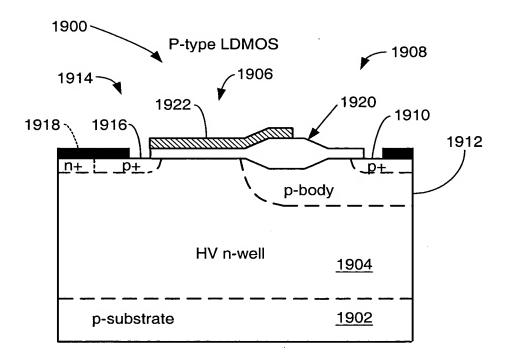
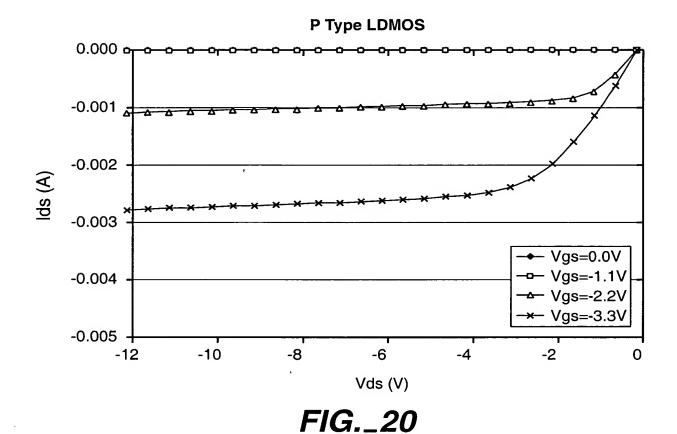


FIG._19



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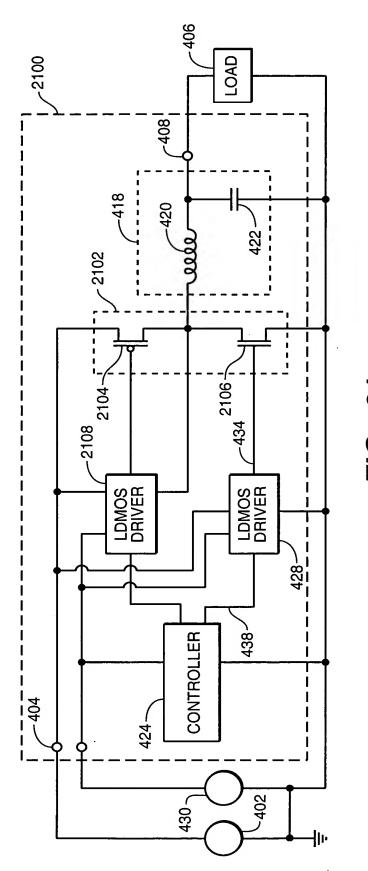
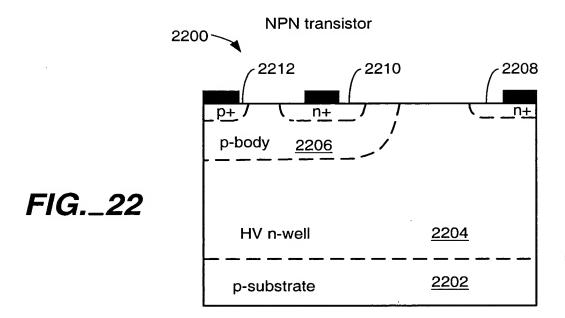
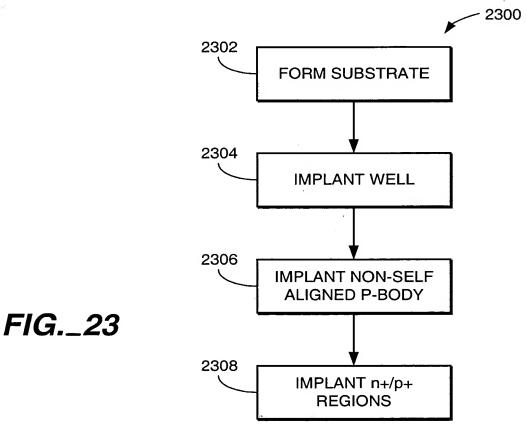
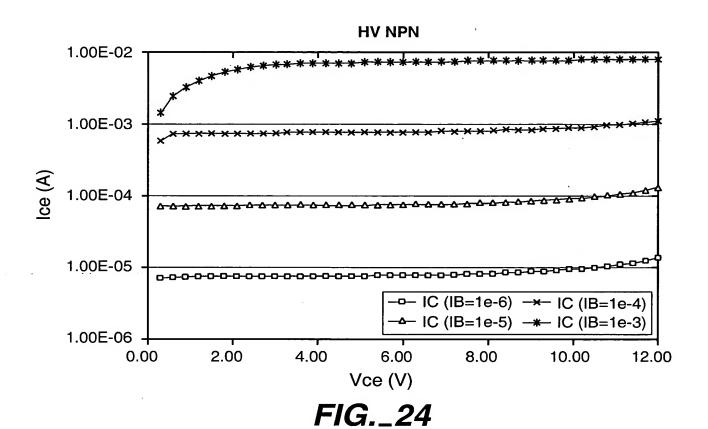


FIG._21

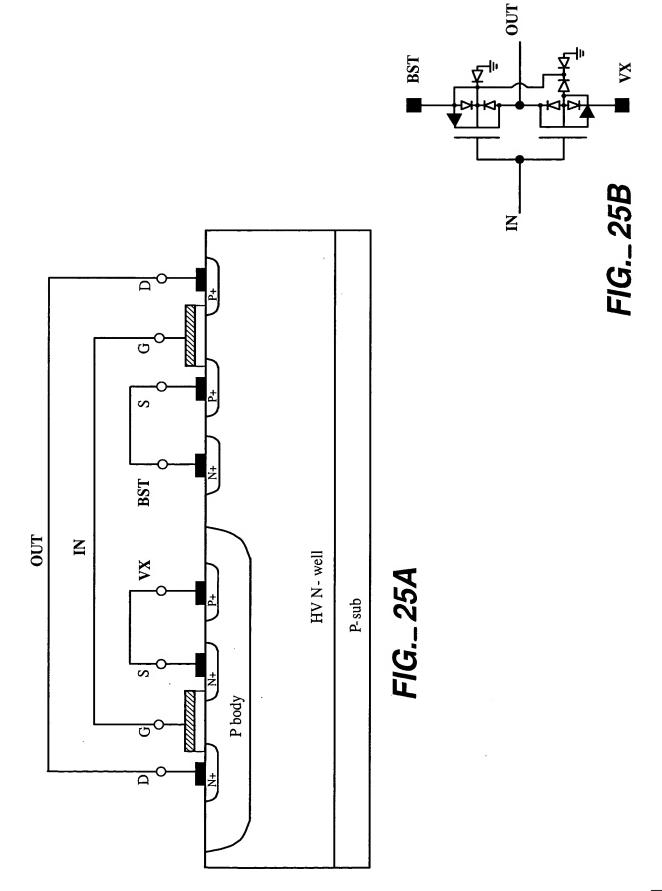
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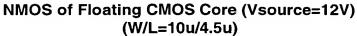




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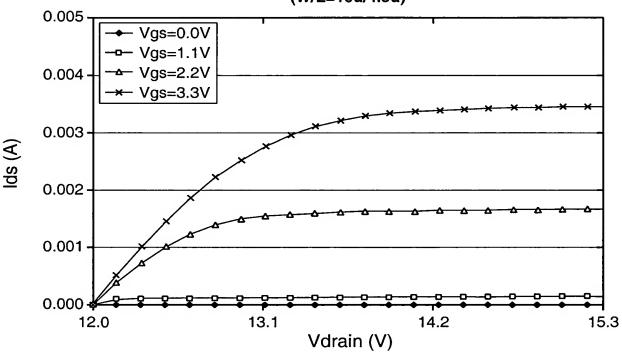
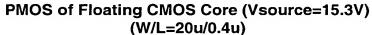


FIG._26A



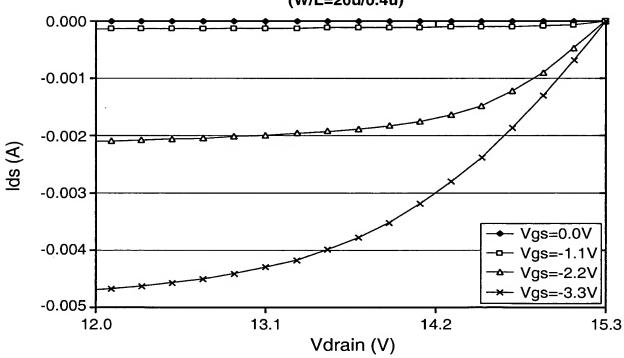


FIG._26B

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